WINSTAR Display

OLED SPECIFICATION

Model No:

WEO004864AWPP3N00000

CUSTOMER :	CL	STO	MER	:
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MODULE NO.: WEO004864AWPP3N00000

APPROVED BY:

(FOR CUSTOMER USE ONLY)

SALES BY	APPROVED BY CHECKED BY	PREPARED BY			
RELEASE DATE:		1			

□ APPROVAL FOR SPECIFICATIONS AND SAMPLE (

MODEL NO:							
REC	ORDS OF REV	ISION	DOC. FIRST ISSUE				
VERSION	DATE	REVISED PAGE NO.	SUMMARY				
0	2017/01/12		First release				
Α	2017/08/31		Modify Reliability test Condition				

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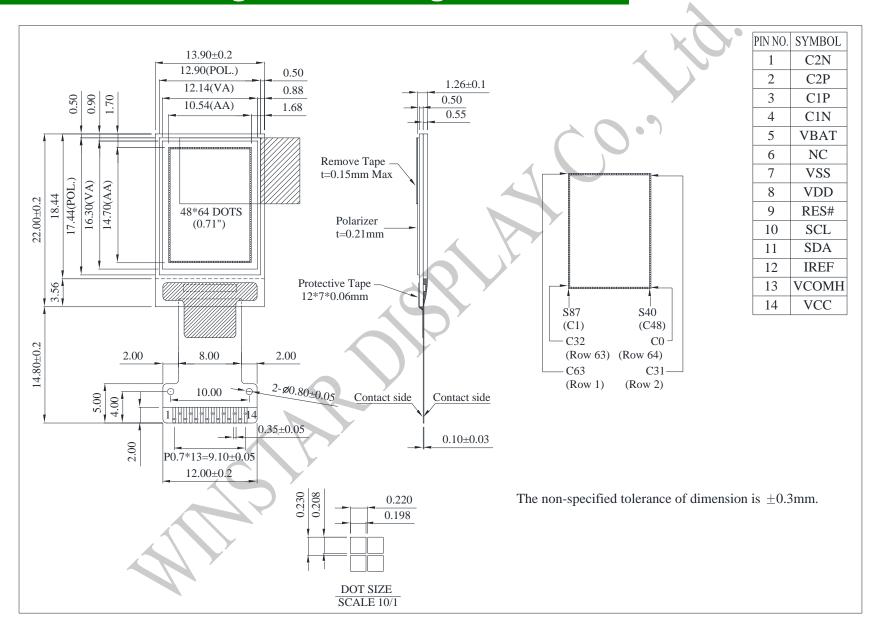
1.Module Classification Information

1	Brand: WINSTA	R DISPLAY CORPORA	TION				
2	E: OLED						
3	Display Type: H	l→Character, G→Graphi	ic , X→TAB ,O→COG	, F→COG (with Frame)			
4	Dot Matrix: 48	* 64		, x (),			
5	Serials code						
		A: Amber	R: Red	C : Full Color			
	Fire itting Color	B: Blue	W: White	. 9			
6	Emitting Color	G: Green	L: Yellow				
		S : Sky Blue	X : Dual Color				
7	Polarizer	P: With Polarizer; N: Without Polarizer					
	1 Olarizei	A : Anti-glare Polarizer					
8	Display Mode	P: Passive Matrix; N: Active Matrix					
9	Driver Voltage	3:3.0~3.3V; 5:5.0V					
10	Touch Panel	N: Without touch panel; T: With touch panel					
11	Product type	0 : Standard 1 : Daylight Readable 2 : Transparent OLED 3 : Flexible OLED (FOI 4 : OLED Lighting	,				
12	Inspection Grade	0 : Standard 2 : Special grade C : Automotive grade Y : Consumer grade					
13	Option	·	C; H: Hot bar FPC; D	Demo Kit			
14	Serial No.	Serial number(00~ZZ)					

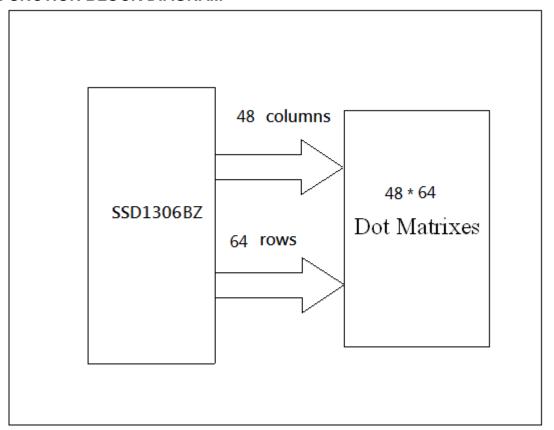
2.General Specification

Item	Dimension	Unit		
Dot Matrix	48 x 64 Dots	_		
Module dimension	13.90× 22.0 × 1.26	mm		
Active Area	10.54×14.70	mm		
Pixel Size	0.198 × 0.208	mm		
Pixel Pitch	0.220 × 0.230	mm		
Display Mode	Passive Matrix	0.		
Display Color	White			
Drive Duty	1/64Duty			
IC	SSD1306BZ			
Interface	I2C			
Size	0.71 inch			

3. Contour Drawing & Block Diagram



FUNCTION BLOCK DIAGRAM



*For more information, please refer to Application Note provided by Winstar

4. Interface Pin Function

No.	Symbol	Function
1	C2N	Basiti a Tanasi ada tala Elija da atia Osasaita Masati a Tanasi ada tala
2	C2P	Positive Terminal of the Flying Inverting Capacitorr Negative Terminal of the
3	C1P	Flying Boost Capacitor The charge-pump capacitors are required between
4	C1N	the terminals. They must be floated when the converter is not used.
5	VBAT	Power Supply for DC/DC Converter Circuit This is the power supply pin for the internal buffer of the DC/DC voltage converter. It must be connected to external source when the converter is used. It should be connected to VDD when the converter is not used.
6	NC	No connection.
7	VSS	Ground of Logic Circuit This is a ground pin. It acts as a reference for the logic pins. It must be connected to external ground.
8	VDD	Power Supply for Logic This is a voltage supply pin. It must be connected to external source.
9	RES#	Power Reset for Controller and Driver This pin is reset signal input. When the pin is low, initialization of the chip is executed.
10	SCL	Host Data Input/Output Bus
11	SDA	When serial mode is selected, D1 will be the serial data input SDIN and D0 will be the serial clock input SCLK. When I2C mode is selected, D2 & D1 should be tired together and serve as SDAout & SDAin in application and D0 is the serial clock input SCL.
12	IREF	Current Reference for Brightness Adjustment This pin is segment current reference pin. A resistor should be connected between this pin and VSS. Set the current lower than 12.5µA.
13	VСОМН	Voltage Output High Level for COM Signal This pin is the input pin for the voltage output high level for COM signals. A capacitor should be connected between this pin and VSS.
14	VCC	Power Supply for OEL Panel This is the most positive voltage supply pin of the chip. A stabilization capacitor should be connected between this pin and VSS when the converter is used. It must be connected to external source when the converter is not used.

5.Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit	Notes
Supply Voltage for Logic	VDD	0	4	V	1,2
Supply Voltage for Display	VCC	0	15	V	1,2
Operating Temperature	TOP	-40	+70	°C	_
Storage Temperature	TSTG	-40	+85	°C	-

Note 1: All the above voltages are on the basis of "VSS = 0V".

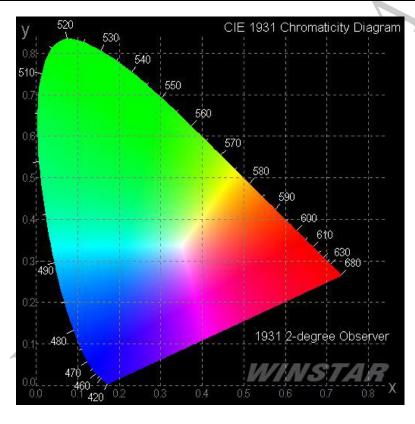
Note 2: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to Section 6."Optics & Electrical Characteristics". If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate.

6.Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage for Logic	VDD	_	2.8	3.0	3.3	V
Supply Voltage for Display	VCC	_	7.0	7.5	8.0	V
Input High Volt.	VIH	_	0.8×VDD	_	VDDIO	V
Input Low Volt.	VIL	_	0	_	0.2×VDD	V
Output High Volt.	VOH	_	0.9×VDD		VDDIO	V
Output Low Volt.	VOL	_	0		0.1×VDD	V
50% Check Board operating Current	ICC	VCC=7.5V	7	15.0	25.0	mA

7.Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
View Angle	(V)θ	_	160	_	_	deg
view / trigic	(Η)φ	_	160	_	_	deg
Contrast Ratio	CR	Dark	2000:1	_	- (_
Response Time	T rise	_	_	10	-/2	μs
Treesponds Time	T fall	_	_	10		μs
Display with 50% chec	k Board Brightness	_	80	100) –	cd/m2
CIEx(White)		(CIE1931)	0.26	0.28	0.30	_
CIEy(White)		(CIE1931)	0.30	0.32	0.34	_



8.OLED Lifetime

ITEM	Conditions	Min	Тур	Remark
Operating Life Time	Ta=25°C / Initial 50% check board brightness Typical Value	20,000 Hrs	_	Note

Notes:

- 1. Life time is defined the amount of time when the luminance has decayed to <50% of the initial value.
- 2. This analysis method uses life data obtained under accelerated conditions to extrapolate an estimated probability density function (*pdf*) for the product under normal use conditions.
- 3. Screen saving mode will extend OLED lifetime.

9.Reliability

Content of Reliability Test

Environmenta	l Test		Ta	
Test Item	Content of Test	Test Condition	Applicable Standard	
High Temperature storage	Endurance test applying the high storage temperature for a long time.	85°C 240hrs		
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-40°C 240hrs		
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 240hrs	7.9	
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-40°C 240hrs		
High Temperature/ Humidity Storage	Endurance test applying the high temperature and high humidity storage for a long time.	60℃,90%RH 240hrs		
High Temperature/ Humidity Operation	Endurance test applying the high temperature and high humidity Operation for a long time.	60°C,90%RH 120hrs		
Temperature Cycle	Endurance test applying the low and high temperature cycle40°C 25°C 80°C 30min 5min 30min	-40°C/80°C 30 cycles		
Mechanical Tes	st			
Vibration test	Endurance test applying the vibration during transportation and using.	Frequency:10~55Hz amplitude:1.5mm Time:0.5hrs/axis Test axis:X,Y,Z		
Others	17	T		
Static electricity test	Endurance test applying the electric stress to the terminal.	Air Discharge model ±4kv,10 times		

Test and measurement conditions

- 1. All measurements shall not be started until the specimens attain to temperature stability. After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure test at 23±5°C; 55±15% RH.
- 2. All-pixels-on is used as operation test pattern.
- 3. The degradation of Polarizer are ignored for High Temperature storage, High Temperature/ Humidity Storage, Temperature Cycle

Evaluation criteria

- 1. The function test is OK.
- 2. No observable defects.
- 3. Luminance: > 50% of initial value.
- 4. Current consumption: within ± 50% of initial value.

APPENDIX:

RESIDUE IMAGE

Because the pixels are lighted in different time, the luminance of active pixels may reduce or differ from inactive pixels. Therefore, the residue image will occur. To avoid the residue image, every pixel needs to be lighted up uniformly.

10.Inspection specification

NO	Item	Criterion				AQL
01	Electrical Testing	1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 OLED viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect.		0.65		
02	Black or white spots on OLED (display only)	2.1 White and black three white or black 2.2 Densely spaced 3mm.	spots p	present.	2000	2.5
03	OLED black spots, white spots, contamina tion (non- display)	3.1 Round type : As following drawing Φ=(x+y)/2 X Y Y		SIZE $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi$	Acceptable Q TY Accept no dense 2	2.5
		3.2 Line type: (As for	ollowing	g drawing)		
		<u>₩</u> L≤	ength ≤ 3.0 ≤ 2.5	$\begin{tabular}{ll} Width & & & \\ W \le 0.02 & & & \\ 0.02 < W \le 0.03 & & \\ 0.03 < W \le 0.05 & & \\ 0.05 < W & & \\ \end{tabular}$	Acceptable Q TY Accept no dense 2 As round type	2.5
04	Polarizer bubbles	If bubbles are visible judge using black specifications, not e to find, must check i specify direction.	oot asy	Size Φ $\Phi \le 0.20$ $0.20 < \Phi \le 0.50$ $0.50 < \Phi \le 1.00$ $1.00 < \Phi$ Total Q TY	Acceptable Q TY Accept no dense 3 2 0 3	2.5

NO	Item				AQL
05	Scratches	Follow NO.3 OLED black spots, white spots, contamination			
			:: Glass thickness a:	Chip thickness OLED side length	
		6.1 General glass chi 6.1.1 Chip on panel s		ween panels:	
			H. H.		>.
	Chipped	z: Chip thickness	y: Chip width	x: Chip length	
		Z≦1/2t	Not over viewing	x≦1/8a	2.5
06	glass	1/2t < z ≦ 2t	area Not exceed 1/3k	x≦1/8a	2.5
		⊙ If there are 2 or mo	re chips, x is total len	gth of each chip.	
		6.1.2 Corner crack:	ZZY		
		X X Z	宝 y		
		THE STATE OF THE S	<u>.</u>		
		z: Chip thickness	v: Chin width	v: Chin length	
		Z≦1/2t	y: Chip width Not over viewing	x: Chip length x≤1/8a	
			area		
		1/2t < z ≦ 2t	Not exceed 1/3k	x≦1/8a	
	⊙If there are 2 or more chips, x is the total length of each ch				

Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: OLED side length L: Electrode pad length 6.2 Protrusion over terminal: 6.2.1 Chip on electrode pad: y: Chip width x: Chip length z: Chip thickness y≤0.5mm x≤1/8a 0 < z≤t 6.2.2 Non-conductive portion: Glass crack y: Chip width x: Chip length z: Chip thickness y≤L x≤1/8a 0 < z≤t Olf the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. ⊙If the product will be heat sealed by the customer, the alignment	NO	Item	Criterion	AQL				
k: Seal width t: Glass thickness a: OLED side length L: Electrode pad length 6.2 Protrusion over terminal : 6.2.1 Chip on electrode pad :								
L: Electrode pad length 6.2 Protrusion over terminal : 6.2.1 Chip on electrode pad :			x: Chip length y: Chip width z: Chip thickness					
6.2 Protrusion over terminal : 6.2.1 Chip on electrode pad : y: Chip width x: Chip length z: Chip thickness y ≤ 0.5mm x ≤ 1/8a 0 < z ≤ t 6.2.2 Non-conductive portion:								
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Glass crack $ \begin{array}{c ccccccccccccccccccccccccccccccccccc$								
Glass crack $y: Chip \ width \qquad x: Chip \ length \qquad z: Chip \ thickness \\ y \leq L \qquad x \leq 1/8a \qquad 0 < z \leq t$ $\bigcirc If \ the \ chipped \ area \ touches \ the \ ITO \ terminal, \ over \ 2/3 \ of \ the \ ITO \ must \ remain \ and \ be \ inspected \ according \ to \ electrode \ terminal \ specifications.$ $\bigcirc If \ the \ product \ will \ be \ heat \ sealed \ by \ the \ customer, \ the \ alignment$								
crack $ y : Chip width $			6.2.2 Non-conductive portion:					
crack $ y : Chip width $								
crack $ y : Chip width $								
y: Chip width x: Chip length z: Chip thickness y ≤ L x ≤ 1/8a 0 < z ≤ t old the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. old the product will be heat sealed by the customer, the alignment	06			2.5				
$y \le L \qquad x \le 1/8a \qquad 0 < z \le t$ $\odot \text{ If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.}$ $\odot \text{ If the product will be heat sealed by the customer, the alignment}$		сгаск	$y \rightarrow \frac{1}{2}$					
$y \le L \qquad x \le 1/8a \qquad 0 < z \le t$ $\odot \text{ If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.}$ $\odot \text{ If the product will be heat sealed by the customer, the alignment}$								
$y \le L \qquad x \le 1/8a \qquad 0 < z \le t$ $\odot \text{ If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.}$ $\odot \text{ If the product will be heat sealed by the customer, the alignment}$			X X					
y ≤ L x ≤ 1/8a 0 < z ≤ t ⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. ⊙ If the product will be heat sealed by the customer, the alignment								
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⊙ If the product will be heat sealed by the customer, the alignment								
		specifications.						
movile not be domoved								
			mark not be damaged. 6.2.3 Substrate protuberance and internal crack.					
y: width x: length			Y .					
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		11						
			9.59					

NO	Item	Criterion	AQL
07	Cracked glass	The OLED with extensive crack is not acceptable.	2.5
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using OLED spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB、COB	 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, OLED pad, zebra pad or screw hold pad, make sure it is smoothed down. 	2.5 2.5 0.65 2.5 2.5 0.65 2.5
11	Soldering	 11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB. 	2.5 2.5 2.5 0.65

12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened. 12.8 Pin type must match type in specification sheet. 12.9 OLED pin loose or missing pins. 12.10 Product packaging must the same as specified on packaging specification sheet. 12.11 Product dimension and structure must conform to product specification sheet.	NO	Item	Criterion	AQL
		General	 12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened. 12.8 Pin type must match type in specification sheet. 12.9 OLED pin loose or missing pins. 12.10 Product packaging must the same as specified on packaging specification sheet. 12.11 Product dimension and structure must conform to 	2.5 0.65 2.5 2.5 2.5 2.5 0.65 0.65 0.65

Check Item	Classification	Criteria
No Display	Major	
Missing Line	Major	
Pixel Short	Major	
Darker Short	Major	
Wrong Display	Major	
Un-uniform B/A x 100% < 70% A/C x 100% < 70%	Major	A Normal B Dark Fixel C Dark Fixel

11.Precautions in use of OLED Modules

Modules

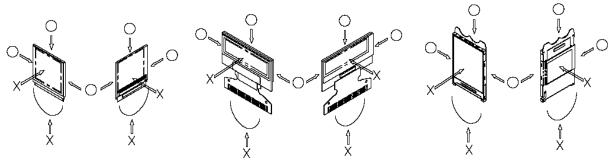
- (1) Avoid applying excessive shocks to module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of OLED display module.
- (3)Don't disassemble the OLED display module.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist OLED display module.
- (6)Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.
- (8)It's pretty common to use "Screen Saver" to extend the lifetime and Don't use fix information for long time in real application.
- (9)Don't use fixed information in OLED panel for long time, that will extend "screen burn" effect time...
- (10) Winstar has the right to change the passive components, including R2 and R3 adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (11)Winstar have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Winstar have the right to modify the version.)

11.1. Handling Precautions

- (1) Since the display panel is being made of glass, do not apply mechanical impacts such us dropping from a high position.
- (2) If the display panel is broken by some accident and the internal organic substance leaks out, be careful not to inhale nor lick the organic substance.
- (3) If pressure is applied to the display surface or its neighborhood of the OLED display module, the cell structure may be damaged and be careful not to apply pressure to these sections.
- (4) The polarizer covering the surface of the OLED display module is soft and easily scratched. Please be careful when handling the OLED display module.
- (5) When the surface of the polarizer of the OLED display module has soil, clean the surface. It takes advantage of by using following adhesion tape.
 - * Scotch Mending Tape No. 810 or an equivalent
 - Never try to breathe upon the soiled surface nor wipe the surface using cloth containing solvent such as ethyl alcohol, since the surface of the polarizer will become cloudy.

Also, pay attention that the following liquid and solvent may spoil the polarizer:

- * Water
- * Ketone
- * Aromatic Solvents
- (6) Hold OLED display module very carefully when placing OLED display module into the System housing. Do not apply excessive stress or pressure to OLED display module. And, do not over bend the film with electrode pattern layouts.
 - These stresses will influence the display performance. Also, secure sufficient rigidity for the outer cases.



- (7) Do not apply stress to the LSI chips and the surrounding molded sections.
- (8) Do not disassemble nor modify the OLED display module.
- (9) Do not apply input signals while the logic power is off.
- (10) Pay sufficient attention to the working environments when handing OLED display modules to prevent occurrence of element breakage accidents by static electricity.
- * Be sure to make human body grounding when handling OLED display modules.
- * Be sure to ground tools to use or assembly such as soldering irons.
- * To suppress generation of static electricity, avoid carrying out assembly work under dry environments.
- * Protective film is being applied to the surface of the display panel of the OLED display module. Be careful since static electricity may be generated when exfoliating the protective film.
- (11) Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. At this time, if the OLED display module has been stored for a long period of time, residue adhesive material of the protection film may remain on the surface of the display panel after removed of the film. In such case, remove the residue material by the method introduced in the above Section 5.
- (12) If electric current is applied when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful to avoid the above.

11.2. Storage Precautions

(1) When storing OLED display modules, put them in static electricity preventive bags avoiding exposure to direct sun light nor to lights of fluorescent lamps. and, also, avoiding high temperature and high humidity environment or low temperature (less than 0°C) environments.

(We recommend you to store these modules in the packaged state when they were shipped from Winstar.

At that time, be careful not to let water drops adhere to the packages or bags nor let dewing occur with them.

(2) If electric current is applied when water drops are adhering to the surface of the OLED display module, when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful about the above.

11.3. Designing Precautions

- (1) The absolute maximum ratings are the ratings which cannot be exceeded for OLED display module, and if these values are exceeded, panel damage may be happen.
- (2) To prevent occurrence of malfunctioning by noise, pay attention to satisfy the VIL and VIH specifications and, at the same time, to make the signal line cable as short as possible.
- (3) We recommend you to install excess current preventive unit (fuses, etc.) to the power circuit (VDD). (Recommend value: 0.5A)
- (4) Pay sufficient attention to avoid occurrence of mutual noise interference with the neighboring devices.
- (5) As for EMI, take necessary measures on the equipment side basically.

- (6) When fastening the OLED display module, fasten the external plastic housing section.
- (7) If power supply to the OLED display module is forcibly shut down by such errors as taking out the main battery while the OLED display panel is in operation, we cannot guarantee the quality of this OLED display module.
- * Connection (contact) to any other potential than the above may lead to rupture of the IC.

11.4. Precautions when disposing of the OLED display modules

1) Request the qualified companies to handle industrial wastes when disposing of the OLED display modules. Or, when burning them, be sure to observe the environmental and hygienic laws and regulations.

11.5. Other Precautions

- (1) When an OLED display module is operated for a long of time with fixed pattern may remain as an after image or slight contrast deviation may occur.
- Nonetheless, if the operation is interrupted and left unused for a while, normal state can be restored. Also, there will be no problem in the reliability of the module.
- (2) To protect OLED display modules from performance drops by static electricity rapture, etc., do not touch the following sections whenever possible while handling the OLED display modules.
- * Pins and electrodes
- * Pattern layouts such as the TCP & FPC
- (3) With this OLED display module, the OLED driver is being exposed. Generally speaking, semiconductor elements change their characteristics when light is radiated according to the principle of the solar battery. Consequently, if this OLED driver is exposed to light, malfunctioning may occur.
- * Design the product and installation method so that the OLED driver may be shielded from light in actual usage.
- * Design the product and installation method so that the OLED driver may be shielded from light during the inspection processes.
- (4) Although this OLED display module stores the operation state data by the commands and the indication data, when excessive external noise, etc. enters into the module, the internal status may be changed. It therefore is necessary to take appropriate measures to suppress noise generation or to protect from influences of noise on the system design.
- (5) We recommend you to construct its software to make periodical refreshment of the operation statuses (re-setting of the commands and re-transference of the display data) to cope with catastrophic noise.
- (6)Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.
- (7)Our company will has the right to upgrade and modify the product function.
- (8) The limitation of FPC bending

